



# Coater/Developer & Hotplate Series

## Uni-body Design Concept

Foot-print outstanding (ref 1.0m\*0.8m)

## Flexible Configuration

Numbers of coater/developer/hotplate customized

## Modular Options

Wide range of options down to module level, including dispense systems, temperature for developers etc.

## Cost or Performance Orientation

Dispense, Pump, Values etc. depending on requirements

## Sample Handling

Open-Load



Specification	Coater	Developer
Wafer Size Range	Small-piece,2,4,6,8,12 inch or Square optional	
Max. Spin Speed	8000 rpm ±1rpm	5000 rpm ±1rpm
Max. Acceleration	8000 rpm/s	5000 rpm/s
Dispense Arm	Up to 2 photeresist lines	Up to 2 developer lines and deionized water line
Interlock	Vacuum pressure, uncover etc.	
Hotplate Specifications		
Wafer Size Range	Small-piece,2,4,6,8,12 inch or Square optional	
Max. Temperature	Up to 200°C, Higher Temperature optional	
Lift-Pins	3 lift-Pins, minimum compatible 2 inch	